May 1999

LM1084 5A Low Dropout Positive Regulators

5A

–40°C to 125°C

0.015% (typical)

0.1% (typical)

National Semiconductor

LM1084 5A Low Dropout Positive Regulators

General Description

The LM1084 is a series of low dropout voltage positive regulators with a maximum dropout of 1.5V at 5A of load current. It has the same pin-out as National Semiconductor's industry standard LM317.

The LM1084 is available in an adjustable version, which can set the output voltage with only two external resistors. It is also available in three fixed voltages: 3.3V, 5.0V and 12.0V. The fixed versions intergrate the adjust resistors.

The LM1084 circuit includes a zener trimmed bandgap reference, current limiting and thermal shutdown.

The LM1084 series is available in TO-220 and TO-263 packages.

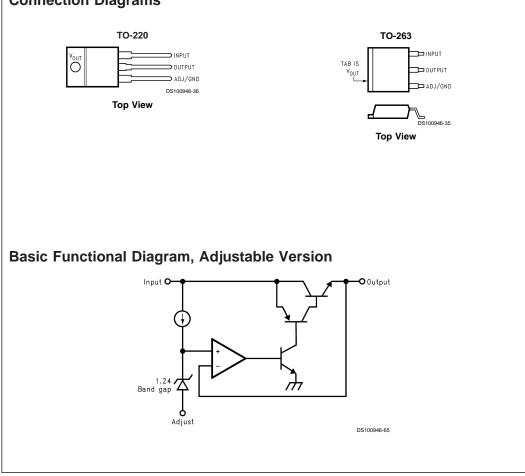
Features

- Available in 3.3V, 5.0V, 12V and Adjustable Versions
- Current Limiting and Thermal Protection
- Output Current
- Industrial Temperature Range
- Line Regulation
- Load Regulation
- -

Applications

- Post Regulator for Switching DC/DC Conveter
- High Efficiency Linear Regulators
- Battery Charger

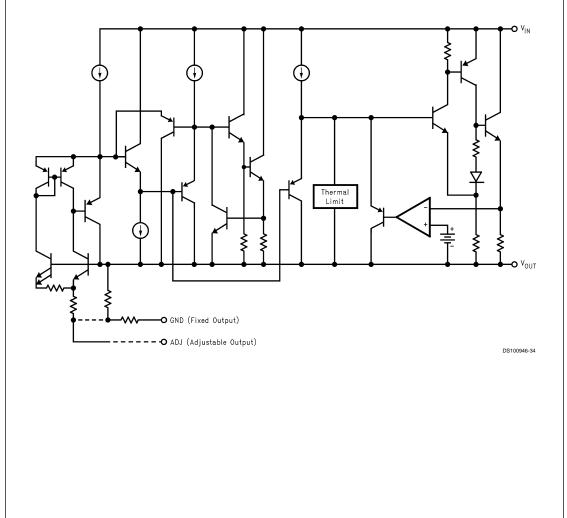
Connection Diagrams



© 1999 National Semiconductor Corporation DS100946

Package	Temperature Range	Part Number	Transport Media	NSC Drawing	
3-lead TO-263	-40°C to +125°C	LM1084IS-ADJ	Rails		
		LM1084ISX-ADJ	Tape and Reel		
		LM1084IS-12	Rails	TS3B	
		LM1084ISX-12	Tape and Reel	1030	
		LM1084IS-3.3	Rails		
		LM1084ISX-3.3	Tape and Reel		
		LM1084IS-5.0	Rails		
		LM1084ISX-5.0	Tape and Reel		
3-lead TO-220	-40°C to + 125°C	LM1084IT-ADJ	Rails		
		LM1084IT-12	Rails	Тозв	
		LM1084IT-3.3	Rails	1036	
		LM1084IT-5.0	Rails	1	

Simplified Schematic



Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications. Junction Temperature (T_J)(Note 3)150°CStorage Temperature Range-65°C to 150°CLead Temperature260°C, to 10 secESD Tolerance (Note 4)2000V

Operating Ratings (Note 1)

Junction Temperature Range (T	J) (Note 3)
Control Section	-40°C to 125°C
Output Section	-40°C to 150°C

Maximum Input to Output Voltage Differential

LM1084-ADJ	29V
LM1084-12	18V
LM1084-3.3	27V
LM1084-5.0	25V
Power Dissipation (Note 2)	Internally Limited

Electrical Characteristics

Typicals and limits appearing in normal type apply for $T_J = 25$ °C. Limits appearing in **Boldface** type apply over the entire junction temperature range for operation.

Symbol	Parameter	Conditions	Min (Note 6)	Typ (Note 5)	Max (Note 6)	Units
V _{REF}	Reference Voltage	$ \begin{array}{l} LM1084\text{-}ADJ \\ I_{OUT} = 10\text{mA}, V_{\text{IN}}\text{-}V_{OUT} = 3V \\ 10\text{mA} \leq I_{OUT} \leq I_{\text{FULL LOAD}}, 1.5V \leq (V_{\text{IN}}\text{-}V_{OUT}) \leq 25V \\ (\text{Note 7}) \end{array} $	1.238 1.225	1.250 1.250	1.262 1.270	v v
001	Output Voltage (Note 7)	LM1084-3.3 $I_{OUT} = 0mA, V_{IN} = 8V$ $0 \le I_{OUT} \le I_{FULL \ LOAD}, 4.8V \le V_{IN} \le 15V$	3.270 3.235	3.300 3.300	3.330 3.365	V V
		$ LM1084-5.0 \\ I_{OUT} = 0mA, V_{IN} = 8V \\ 0 \le I_{OUT} \le I_{FULL \ LOAD}, \ 6.5V \le V_{IN} \le 20V $	4.950 4.900	5.000 5.000	5.050 5.100	V V
		$ \begin{array}{l} LM1084\text{-}12\\ I_{OUT}=0\text{mA},\ V_{\text{IN}}=15\text{V}\\ 0\leq I_{OUT}\leq I_{FULL\ LOAD},\ 13.5\text{V}\leq V_{\text{IN}}\leq 25\text{V} \end{array} $	11.880 11.760	12.000 12.000	12.120 12.240	V V
(Note	Line Regulation (Note 8)	LM1084-ADJ I_{OUT} =10mA, 1.5V \leq (V _{IN} -V _{OUT}) \leq 15V LM1084-3.3		0.015 0.035 0.5	0.2 0.2 6	% % m\
		$\label{eq:Interm} \begin{array}{ c c c c c } I_{OUT} = 0mA, 4.8V \leq V_{IN} \leq 15V \\ \hline \\ LM1084-5.0 \\ I_{OUT} = 0mA, 6.5V \leq V_{IN} \leq 20V \\ \end{array}$		1.0 0.5 1.0	6 10 10	m\ m\ m\
		$\label{eq:limit} \begin{array}{l} LM1084\text{-}12\\ I \\ _{OUT} = 0mA, \ 13.5V \leq V_{IN} \leq 25V \end{array}$		1.0 2.0	25 25	m\ m\
ΔV _{OUT}	Load Regulation (Note 8)	$\label{eq:loss} \begin{array}{l} LM1084\text{-}ADJ\\ (V_{\text{IN}}\text{-}V_{\text{OUT}}) = 3V, \ 10\text{mA} \leq I_{\text{OUT}} \leq I_{\text{FULL LOAD}}\\ \hline\\ LM1084\text{-}3.3 \end{array}$		0.1 0.2 3	0.3 0.4 15	% % m\
		$V_{IN} = 5V, 0 \le I_{OUT} \le I_{FULL \ LOAD}$ $LM1084-5.0$ $V_{IN} = 8V, 0 \le I_{OUT} \le I_{FULL \ LOAD}$		7 5 10	20 20 35	m\ m\ m\
		LM1084-12 V_{IN} = 15V, 0 ≤ I_{OUT} ≤ $I_{FULL LOAD}$		12 24	36 72	m\ m\
	Dropout Voltage (Note 9)	LM1084-3.3/5/12/ADJ ΔV_{REF} = 1%, I _{OUT} = 3A		1.3	1.5	v

Symbol	Parameter	Conditions	Min (Note 6)	Typ (Note 5)	Max (Note 6)	Unit
ILIMIT	Current Limit	LM1084-ADJ	,	,	,	
		$V_{IN} - V_{OUT} = 5V$	5.5	6.5		A
		$V_{IN}-V_{OUT} = 25V$	0.3	0.6		A
		LM1084-3.3				
		V _{IN} = 8V	5.5	6.5		A
		LM1084-5.0				
		V _{IN} = 10V	5.5	6.5		A
		LM1084-12				
		V _{IN} = 17V	5.5	6.5		A
	Minimum Load	LM1084-ADJ				
	Current (Note	$V_{IN} - V_{OUT} = 25V$				
	10)			5	10.0	m/
	Quiescent	LM1084-3.3				
	Current	V _{IN} = 18V		5.0	10.0	m/
		LM1084-5.0				
		$V_{IN} \le 20V$		5.0	10.0	m/
		LM1084-12				
		$V_{IN} \le 25V$		5.0	10.0	m/
	Thermal Regulation	$T_A = 25^{\circ}C$, 30ms Pulse		0.003	0.015	%/\
	Ripple Rejection	$f_{RIPPLE} = 120Hz$, = $C_{OUT} = 25\mu F$ Tantalum, $I_{OUT} = 5A$				
		LM1084-ADJ, C_{ADJ} , = 25µF, $(V_{IN}-V_O)$ = 3V	60	75		dE
		LM1084-3.3, V _{IN} = 6.3V	60	72		dE
		LM1084-5.0, V _{IN} = 8V	60	68		dE
		LM1084-12 V _{IN} = 15V	54	60		dE
	Adjust Pin Current	LM1084		55	120	μA
	Adjust Pin Current Change	$10\text{mA} \le I_{\text{OUT}} \le I_{\text{FULL LOAD}},$ $1.5\text{V} \le \text{V}_{\text{IN}} - \text{V}_{\text{OUT}} \le 25\text{V}$		0.2	5	μA
	Temperature Stability			0.5		%
	Long Term Stability	T _A =125°C, 1000Hrs		0.3	1.0	%
	RMS Output Noise (% of V _{OUT})	10Hz ≤ f≤ 10kHz		0.003		%
	Thermal Resistance Junction-to-Case	3-Lead TO-263: Control Section/Output Section 3-Lead TO-220: Control Section/Output Section			0.65/2.7 0.65/2.7	°C/\ °C/\

Note 3: The maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. All numbers apply for packages soldered directly into a PC board. Refer to Thermal Considerations in the Application Notes.

Note 4: For testing purposes, ESD was applied using human body model, $1.5k\Omega$ in series with 100pF.

Note 5: Typical Values represent the most likely parametric norm. Note 6: All limits are guaranteed by testing or statistical analysis.

Note 7: IFULLLOAD is defined in the current limit curves. The IFULLOAD Curve defines the current limit as a function of input-to-output voltage. Note that 30W power dissipation for the LM1084 is only achievable over a limited range of input-to-output voltage.

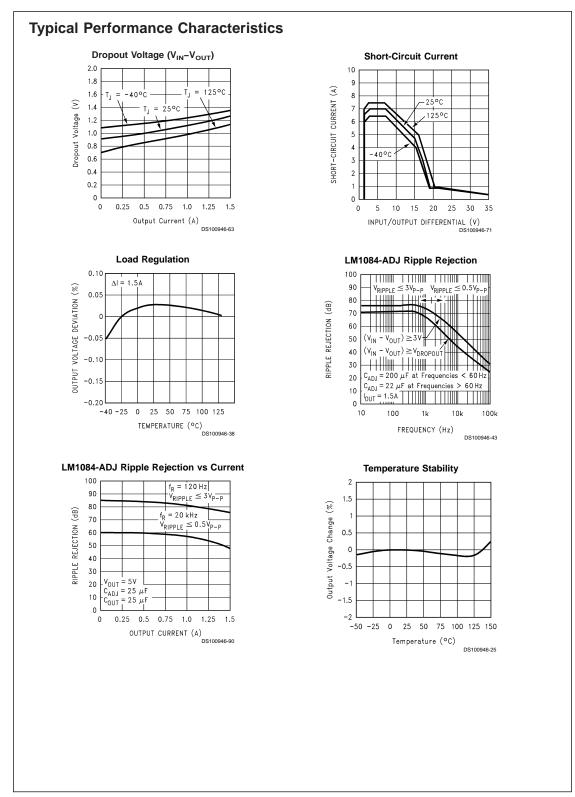
Note 8: Load and line regulation are measured at constant junction temperature, and are guaranteed up to the maximum power dissipation of 30W. Power dissipation is determined by the input/output differential and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range. Note 9: Dropout voltage is specified over the full output current range of the device.

www.national.com

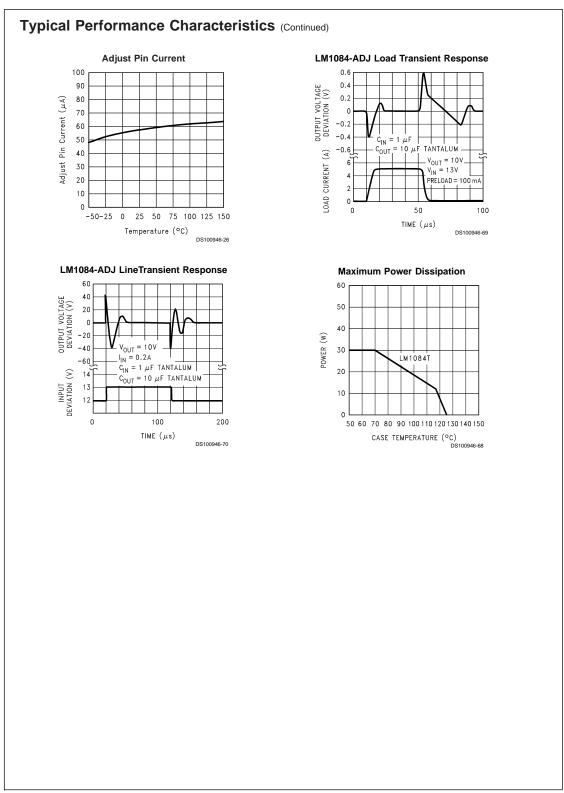
.

Electrical Characteristics (Continued)

Note 10: The minimum output current required to maintain regulation.



6



APPLICATION NOTE

General

Figure 1 shows a basic functional diagram for the LM1084-Adj (excluding protection circuitry). The topology is basically that of the LM317 except for the pass transistor. Instead of a Darlingtion NPN with its two diode voltage drop, the LM1084 uses a single NPN. This results in a lower dropout voltage. The structure of the pass transistor is also known as a quasi LDO. The advantage a quasi LDO over a PNP LDO is its inherently lower quiescent current. The LM1084 is guaranteed to provide a minimum dropout voltage 1.5V over temperature, at full load.

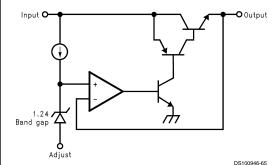


FIGURE 1. Basic Functional Diagram for the LM1084, excluding Protection circuitry

Output Voltage

The LM1084 adjustable version develops at 1.25V reference voltage, (V_{REF}), between the output and the adjust terminal. As shown in figure 2, this voltage is applied across resistor R1 to generate a constant current I1. This constant current then flows through R2. The resulting voltage drop across R2 adds to the reference voltage to sets the desired output voltage.

The current I_{ADJ} from the adjustment terminal introduces an output error . But since it is small (120uA max), it becomes negligible when R1 is in the 100 Ω range.

For fixed voltage devices, R1 and R2 are integrated inside the devices.

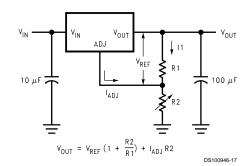


FIGURE 2. Basic Adjustable Regulator

Stability Consideration

Stability consideration primarily concern the phase response of the feedback loop. In order for stable operation, the loop must maintain negative feedback. The LM1084 requires a certain amount series resistance with capacitive loads. This series resistance introduces a zero within the loop to increase phase margin and thus increase stability. The equivalent series resistance (ESR) of solid tantalum or aluminum electrolytic capacitors is used to provide the appropriate zero (approximately 500 kHz).

The Aluminum electrolytic are less expensive than tantalums, but their ESR varies exponentially at cold temperatures; therefore requiring close examination when choosing the desired transient response over temperature. Tantalums are a convenient choice because their ESR varies less than 2:1 over temperature.

The recommended load/decoupling capacitance is a 10 $\rm IF$ tantalum or a 50 $\rm IF$ aluminum. These values will assure stability for the majority of applications.

The adjustable versions allows an additional capacitor to be used at the ADJ pin to increase ripple rejection. If this is done the output capacitor should be increased to 22uF for tantalums or to 150uF for aluminum.

Capacitors other than tantalum or aluminum can be used at the adjust pin and the input pin. A 10uF capacitor is a reasonable value at the input. See Ripple Rejection section regarding the value for the adjust pin capacitor.

It is desirable to have large output capacitance for applications that entail large changes in load current (microprocessors for example). The higher the capacitance, the larger the available charge per demand. It is also desirable to provide low ESR to reduce the change in output voltage:

 $\Delta V = \Delta I \times ESR$

It is common practice to use several tantalum and ceramic capacitors in parallel to reduce this change in the output voltage by reducing the overall ESR.

Output capacitance can be increased indefinitely to improve transient response and stability.

Ripple Rejection

Ripple rejection is a function of the open loop gain within the feed-back loop (refer to *Figure 1* and *Figure 2*). The LM1084 exhibits 75dB of ripple rejection (typ.). When adjusted for voltages higher than V_{REF} , the ripple rejection decreases as function of adjustment gain: (1+R1/R2) or V_O/V_{REF} . Therefore a 5V adjustment decreases ripple rejection by a factor of four (-12dB); Output ripple increases as adjustment voltage increases.

However, the adjustable version allows this degradation of ripple rejection to be compensated. The adjust terminal can be bypassed to ground with a capacitor (C_{ADJ}). The impedance of the C_{ADJ} should be equal to or less than R1 at the desired ripple frequency. This bypass capacitor prevents ripple from being amplified as the output voltage is increased.

 $1/(2\pi^* f_{RIPPLE}^* C_{ADJ}) \le R_1$

Load Regulation

The LM1084 regulates the voltage that appears between its output and ground pins, or between its output and adjust pins. In some cases, line resistances can introduce errors to the voltage across the load. To obtain the best load regulation, a few precautions are needed.

Figure 3 shows a typical application using a fixed output regulator. Rt1 and Rt2 are the line resistances. V_{LOAD} is less than the V_{OUT} by the sum of the voltage drops along the line resistances. In this case, the load regulation seen at the R_{LOAD} would be degraded from the data sheet specification.

APPLICATION NOTE (Continued)

To improve this, the load should be tied directly to the output terminal on the positive side and directly tied to the ground terminal on the negative side.

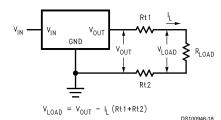


FIGURE 3. Typical Application using Fixed Output Regulator

When the adjustable regulator is used (*Figure 4*), the best performance is obtained with the positive side of the resistor R1 tied directly to the output terminal of the regulator rather than near the load. This eliminates line drops from appearing effectively in series with the reference and degrading regulation. For example, a 5V regulator with 0.05\Omega resistance between the regulator and load will have a load regulation due to line resistance of $0.05\Omega \times I_L$. If R1 (=125 Ω) is connected near the load the effective line resistance will be 0.05Ω (1 + R2/R1) or in this case, it is 4 times worse. In addition, the ground of the load to provide remote ground sensing and improve load regulation.

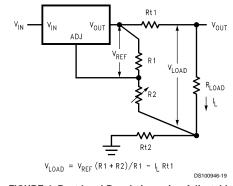


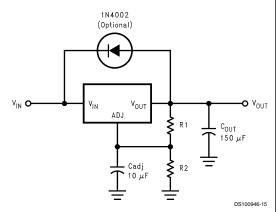
FIGURE 4. Best Load Regulation using Adjustable Output Regulator

3.0 Protection Diodes

Under normal operation, the LM1084 regulator does not need any protection diode. With the adjustable device, the internal resistance between the adjustment and output terminals limits the current. No diode is needed to divert the current around the regulator even with a capacitor on the adjustment terminal. The adjust pin can take a transient signal of ±25V with respect to the output voltage without damaging the device.

When an output capacitor is connected to a regulator and the input is shorted, the output capacitor will discharge into the output of the regulator. The discharge current depends on the value of the capacitor, the output voltage of the regulator, and rate of decrease of $V_{\rm IN}$. In the LM1084 regulator, the internal diode between the output and input pins can

withstand microsecond surge currents of 10A to 20A. With an extremely large output capacitor ($\geq 1000 \ \mu$ f), and with input instantaneously shorted to ground, the regulator could be damaged. In this case, an external diode is recommended between the output and input pins to protect the regulator, shown in *Figure 5*.





Overload Recovery

Overload recovery refers to regulator's ability to recover from a short circuited output. A key factor in the recovery process is the current limiting used to protect the output from drawing too much power. The current limiting circuit reduces the output current as the input to output differential increases. Refer to short circuit curve in the curve section.

During normal start-up, the input to output differential is small since the output follows the input. But, if the output is shorted, then the recovery involves a large input to output differential. Sometimes during this condition the current limiting circuit is slow in recovering. If the limited current is too low to develop a voltage at the output, the voltage will stabilize at a lower level. Under these conditions it may be necessary to recycle the power of the regulator in order to get the smaller differential voltage and thus adequate start up conditions. Refer to curve section for the short circuit current vs. input differential voltage.

Thermal Considerations

ICs heats up when in operation, and power consumption is one factor in how hot it gets. The other factor is how well the heat is dissipated. Heat dissipation is predictable by knowing the thermal resistance between the IC and ambient (θ_{JA}). Thermal resistance has units of temperature per power (C/W). The higher the thermal resistance, the hotter the IC. The LM1084 specifies the thermal resistance for each package as junction to case (θ_{JC}). In order to get the total resistance to ambient (θ_{JA}), two other thermal resistance must be added, one for case to heat-sink (θ_{CH}) and one for heatsink to ambient (θ_{HA}). The junction temperature can be predicted as follows:

 $\mathsf{T}_\mathsf{J} = \mathsf{T}_\mathsf{A} + \mathsf{P}_\mathsf{D} \; (\theta_\mathsf{JC} + \theta_\mathsf{CH} + \theta_\mathsf{HA}) = \mathsf{T}_\mathsf{A} + \mathsf{P}_\mathsf{D} \; \theta_\mathsf{JA}$

 $T_{\rm J}$ is junction temperature, $T_{\rm A}$ is ambient temperature, and $P_{\rm D}$ is the power consumption of the device. Device power consumption is calculated as follows:

$$\begin{split} I_{\text{IN}} &= I_{\text{L}} + I_{\text{G}} \\ P_{\text{D}} &= (V_{\text{IN}} - V_{\text{OUT}}) \ I_{\text{L}} + V_{\text{IN}} I_{\text{G}} \end{split}$$

APPLICATION NOTE (Continued)

Figure 6 shows the voltages and currents which are present in the circuit.

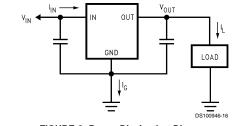


FIGURE 6. Power Dissipation Diagram

Once the devices power is determined, the required θ_{JA} is calculated as:

 $\theta_{JA (min)} = T_R(max)/P_D = T_J(max) - T_A(max)/P_D$

The LM1084 specifies maximum junction temperature for two sections of the IC. One for the control section and one for the output section. The control section's maximum temperature is 125°C for specified operation, while the maximum temperature for the output section is 150°C before damage occurs. Both have different junction to case thermal resistances (See specification table).

The maximum power dissipation curve in the curve section illustrates the difference between control and output sections. The two negative slopes correspond to their different thermal resistances and their different maximum temperature intersects. The float slope corresponds to the maximum power of the IC itself, regardless of package considerations.

 $\theta_{JA}~(\text{min})$ should be calculated for each section. That is $\theta_{JA}~(\text{min})$ should be calculated using 125°C for $T_J(max)$ and again using 150°C for $T_J(max)$. Each of these calculation should checked against their respective θ_{JC} given in data table. If each calculation shows as less than $\theta_{JA}(\text{min})$ for each respective section, then no heatsink is require.

If a heatsink is required, Its required thermal resistance can be calculated as follows:

 $\theta_{HA(min)} = \theta_{JA(min)} - (\theta_{JC} + \theta_{CH})$

Once the required thermal resistance for the heat sink is known, the size of the heat sink can be determined from *Figure 7*, which is based on PC board copper and no air flow.

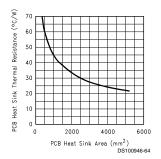
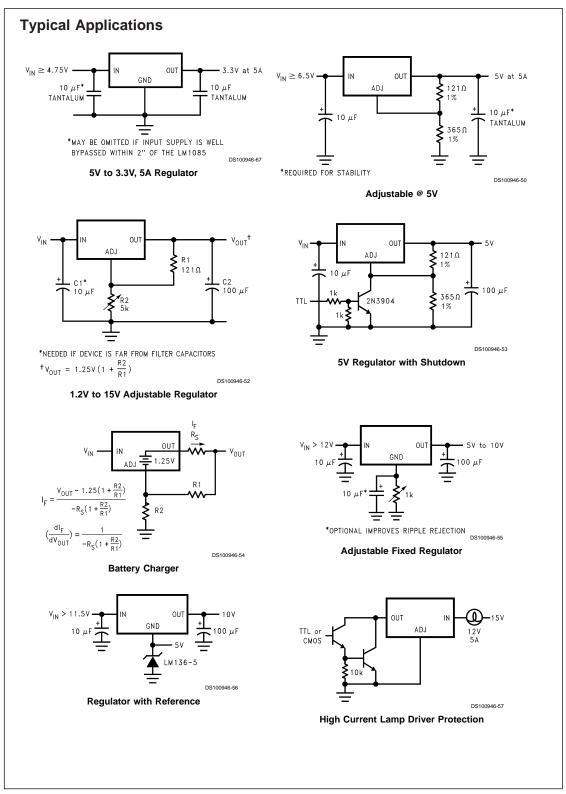
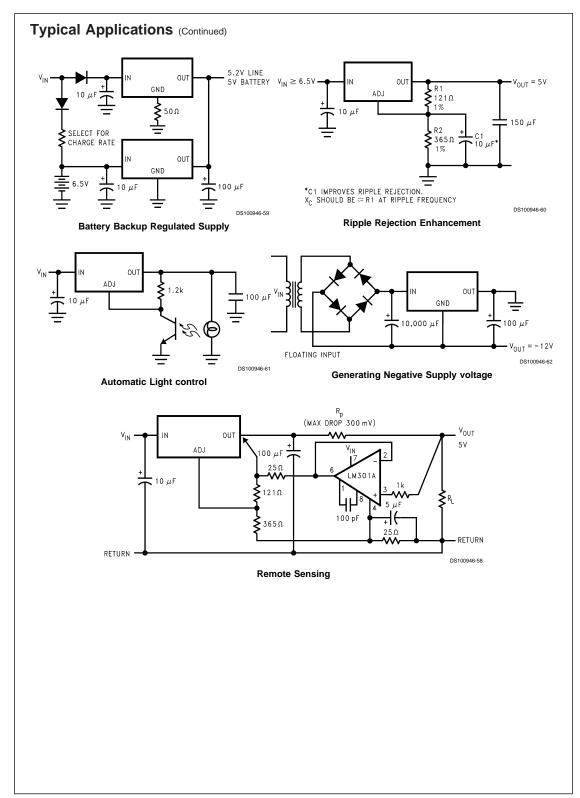


FIGURE 7. Heat sink thermal Resistance vs Area





12

